

Product / Process Change Notification



N° 2019-133-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Change of lead-frame supplier affecting ATSLP packages from Infineon Technologies (Malaysia) Sdn. Bhd.

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **11th November 2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: “**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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► **Products affected:** Please refer to attached affected product list 1_cip19133_a

► **Detailed Change Information:**

Subject: Change of lead-frame supplier affecting ATSLP packages from Infineon Technologies (Malaysia) Sdn. Bhd

Reason:

- Infineon supplier AAPM has announced discontinuation of its lead-frame business by end of 2019
- Change to Infineon lead-frame supplier QDOS, who is already active for other Infineon components, to assure supply continuity

Description:

Leadframe supplier

Old

■ AAPM - ASM Advanced Packaging Materials Pte Ltd (Singapore)

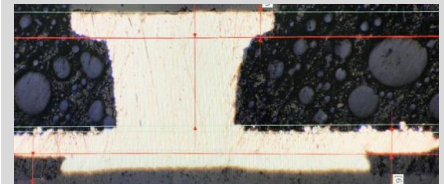
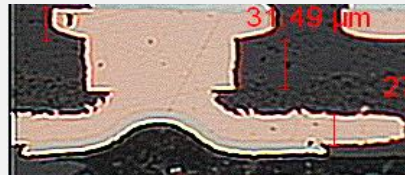
New

■ Qdos Flexcircuits Sdn. Bhd. (Malaysia)

Remark: Cross-section comparison

■ AAPM - ASM Advanced Packaging Materials Pte Ltd (Singapore)

■ Qdos Flexcircuits Sdn. Bhd. (Malaysia)



► **Product Identification:** Internal traceability ensured via baunumber, lot number & date code. No change in SP ordering number.

► **Impact of Change:** Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability

► **Attachments:** 1_cip19133_a: Affected product list

► **Time Schedule:**

- Final qualification report: expected 31-October-2019
- First samples available: expected 15-October-2019
- Intended start of delivery: January-2020 or earlier, depending on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

PCN 2019-133-A

Change of lead-frame supplier affecting ATSLP packages from
Infineon Technologies (Malaysia) Sdn. Bhd.



Sales name	SP number	OPN	Package
BGA H1A10 E6327	SP002641708	BGAH1A10E6327XTSA1	PG-ATSLP-10
BGA U1A10 E6327	SP001628070	BGAU1A10E6327XTSA1	PG-ATSLP-10
BGA V1A10 E6327	SP001628074	BGAV1A10E6327XTSA1	PG-ATSLP-10
BGM 12LBA9 E6327	SP001579876	BGM12LBA9E6327XTSA1	PG-ATSLP-9
BGM 13HBA9 E6327	SP001510046	BGM13HBA9E6327XTSA1	PG-ATSLP-9
BGM 15LA12 E6327	SP001215968	BGM15LA12E6327XTSA1	PG-ATSLP-12
BGS 14MA11 E6327	SP001615916	BGS14MA11E6327XTSA1	PG-ATSLP-11
BGS 14MPA9 E6327	SP001700518	BGS14MPA9E6327XTSA1	PG-ATSLP-9
BGS 16GA14 E6327	SP001313540	BGS16GA14E6327XTSA1	PG-ATSLP-14
BGS 16MA12 E6327	SP001646658	BGS16MA12E6327XTSA1	PG-ATSLP-12
BGS 18GA14 E6327	SP001313548	BGS18GA14E6327XTSA1	PG-ATSLP-14
BGS 18MA12 E6327	SP001646662	BGS18MA12E6327XTSA1	PG-ATSLP-12
BGSX 210MA18 E6327	SP001408614	BGSX210MA18E6327XTSA1	PG-ATSLP-18
BGSX 212MA18 E6327	SP001408616	BGSX212MA18E6327XTSA1	PG-ATSLP-18
BGSX 44MA12 E6327	SP001716962	BGSX44MA12E6327XTSA1	PG-ATSLP-12